

BT136X-600E

Rev.01 - 17 April 2018

Product data sheet

1. General description

Planar passivated sensitive gate four quadrant triac in a SOT186A (TO-220F) plastic package intended for use in general purpose bidirectional switching and phase control applications. This sensitive gate "series E" triac is intended to be interfaced directly to microcontrollers, logic integrated circuits and other low power gate trigger circuits.

2. Features and benefits

- High blocking voltage capability
- Planar passivated for voltage ruggedness and reliability
- Sensitive gate
- Triggering in all four quadrants
- Isolated package
- Direct triggering from low power drivers and logic ICs
- · Low holding current for small load currents and lowest EMI at commutation

3. Applications

- General purpose motor control
- · General purpose switching

4. Quick reference data

| Symbol | Parameter | Conditions | Values | | | Unit | |
|---------------------|--|--|--------|-----|-----|------|------|
| Absolute | e maximum rating | · | I | | | | |
| V _{DRM} | repetitive peak off-state voltage | | | 6 | 00 | | V |
| I _{T(RMS)} | RMS on-state current | full sine wave; T _h ≤92 °C; <u>Fig. 1; Fig. 2; Fig. 3</u> | | 4 | | A | |
| I _{TSM} | non-repetitive peak on- state current | full sine wave; T _{j(init)} = 25 °C; t _p = 20 ms; <u>Fig. 4</u> ; <u>Fig. 5</u> | | 25 | | | A |
| Symbol | Parameter | Conditions | I | Min | Тур | Max | Unit |
| Static ch | aracteristics | | · · · | | | | |
| I _{GT} | gate trigger current | V _D = 12 V; I _T = 0.1 A; T2+ G+; T _j = 25 °C; <u>Fig. 7</u> | - | | 2.5 | 10 | mA |
| | | $V_{D} = 12 \text{ V}; \text{ I}_{T} = 0.1 \text{ A}; \text{ T2+ G-};$ T _j = 25 °C; Fig. 7 | - | | 4 | 10 | mA |
| | | V _D = 12 V; I _T = 0.1 A; T2- G-; T _j = 25 °C; <u>Fig. 7</u> | - | | 5 | 10 | mA |
| | | V _D = 12 V; I _T = 0.1 A; T2- G+; T _j = 25 °C; <u>Fig. 7</u> | - | | 11 | 25 | mA |
| I _H | holding current | V _D = 12 V; T _i = 25 °C; <u>Fig. 9</u> | | | 2.2 | 15 | mA |

5. Pinning information

| Table 2. | Pinning info | rmation | | |
|----------|---------------------|-------------------------|--------------------|----------------|
| Pin | Symbol | Description | Simplified outline | Graphic symbol |
| 1 | T1 | main terminal 1 | mb | |
| 2 | T2 | main terminal 2 | | Ν |
| 3 | G | gate | | |
| mb | n.c. | mounting base; isolated | | sym051 |
| | | | | |
| | | | | |
| | | | | |
| | | | 1 2 3 | |

6. Ordering information

| Table 3. Ordering information | | | | | | |
|-------------------------------|---------|--|---------|--|--|--|
| Type number | Package | ckage | | | | |
| | Name | Description | Version | | | |
| BT136X-600E | TO-220F | plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 3-lead TO-220 "full pack" | SOT186A | | | |

7. Marking

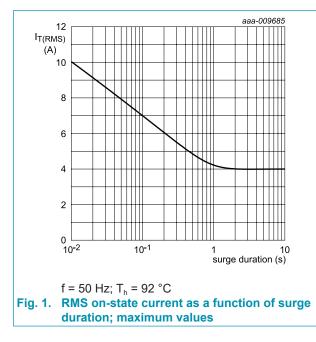
| Table 4. Marking codes | | | | | | | |
|------------------------|---------------|--|--|--|--|--|--|
| Type number | Marking codes | | | | | | |
| BT136X-600E | BT136X-600E | | | | | | |

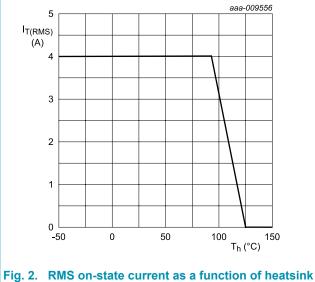
8. Limiting values

Table 5. Limiting values

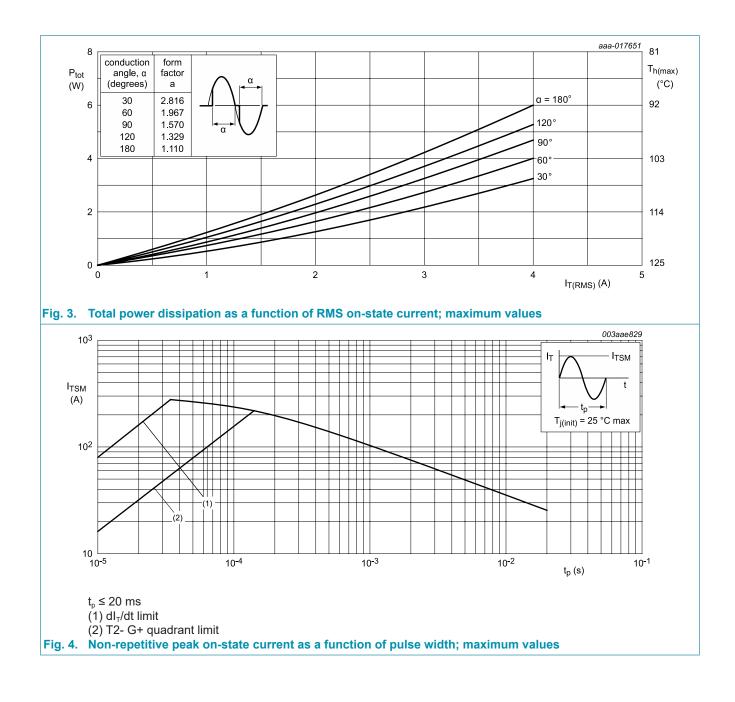
In accordance with the Absolute Maximum Rating System (IEC 60134).

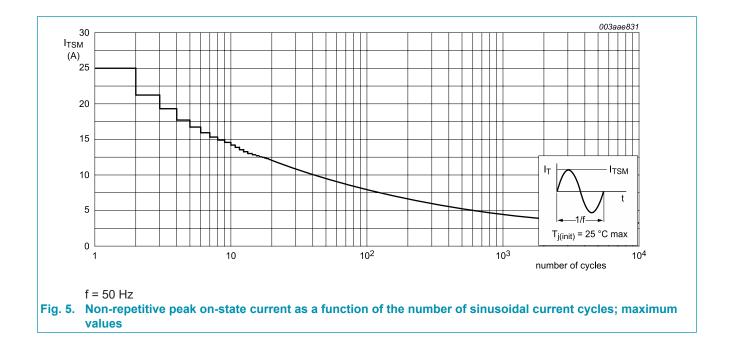
| Symbol | Parameter | Conditions | Values | Unit |
|---------------------|--|---|------------|------------------|
| V_{DRM} | repetitive peak off-state voltage | | 600 | V |
| I _{T(RMS)} | RMS on-state current | full sine wave; T _h ≤92 °C; <u>Fig 1</u> ; <u>Fig 2</u> ; <u>Fig 3</u> | 4 | A |
| I _{TSM} | non-repetitive peak on- state current | full sine wave; T _{j(init)} = 25 °C; t _p = 20 ms; Fig 4; Fig 5 | 25 | A |
| | | full sine wave; $T_{j(init)}$ = 25 °C; t_p = 16.7 ms | 27 | А |
| l ² t | I ² t for fusing | t _P = 10 ms; SIN | 3.1 | A ² s |
| dl _⊤ /dt | rate of rise of on-state current | I _G = 20 mA; T2+ G+ | 50 | A/µs |
| | | I _G = 20 mA; T2+ G- | 50 | A/µs |
| | | I _G = 20 mA; T2- G- | 50 | A/µs |
| | | I _G = 50 mA; T2- G+ | 10 | A/µs |
| I _{GM} | peak gate current | | 2 | А |
| P _{GM} | peak gate power | | 5 | W |
| P _{G(AV)} | average gate power | over any 20 ms period | 0.5 | W |
| T _{stg} | storage temperature | | -40 to 150 | °C |
| Tj | junction temperature | | 125 | °C |





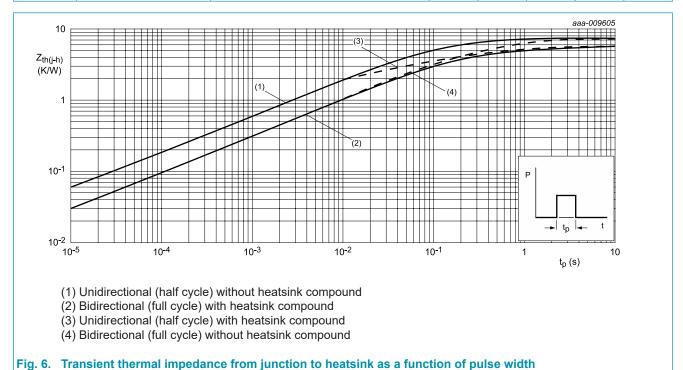
temperature; maximum values





9. Thermal characteristics

| Symbol | Parameter | Conditions | Min | Тур | Max | Unit |
|----------------------|---|--|-----|-----|-----|------|
| $R_{\text{th(j-h)}}$ | thermal resistance from junction to | full or half cycle; with heatsink compound; Fig 6 | - | - | 5.5 | K/W |
| | heatsink | full or half cycle; without heatsink compound; Fig 6 | - | - | 7.2 | K/W |
| $R_{\text{th(j-a)}}$ | thermal resistance from junction to ambient | in free air | - | 55 | - | K/W |

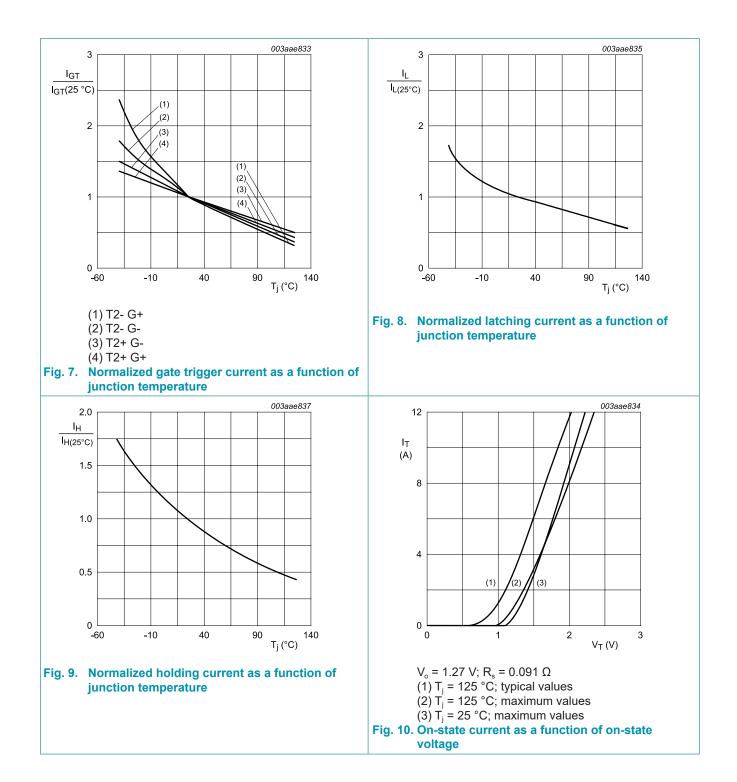


10. Isolation characteristics

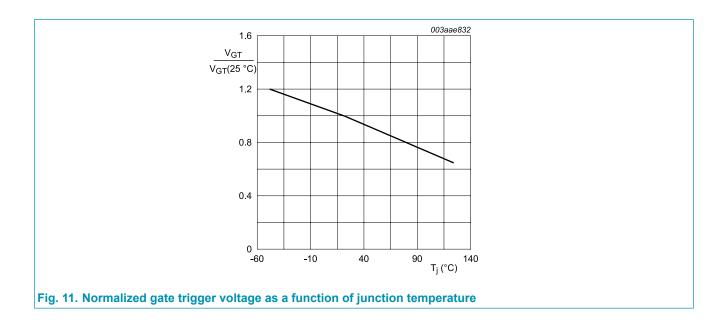
| Fable 7. Isolation characteristics | | | | | | | | |
|------------------------------------|-----------------------|---|--|-----|-----|------|------|--|
| Symbol | Parameter | Conditions | | Min | Тур | Max | Unit | |
| $V_{isol(RMS)}$ | RMS isolation voltage | from all terminals to external heatsink; sinusoidal waveform; clean and dust free; 50 Hz \leq f \leq 60 Hz; RH \leq 65 %; T _h = 25 °C | | - | - | 2500 | V | |
| C _{isol} | isolation capacitance | from main terminal 2 to external heatsink; f = 1 MHz; T_h = 25 °C | | - | 10 | - | pF | |

11. Characteristics

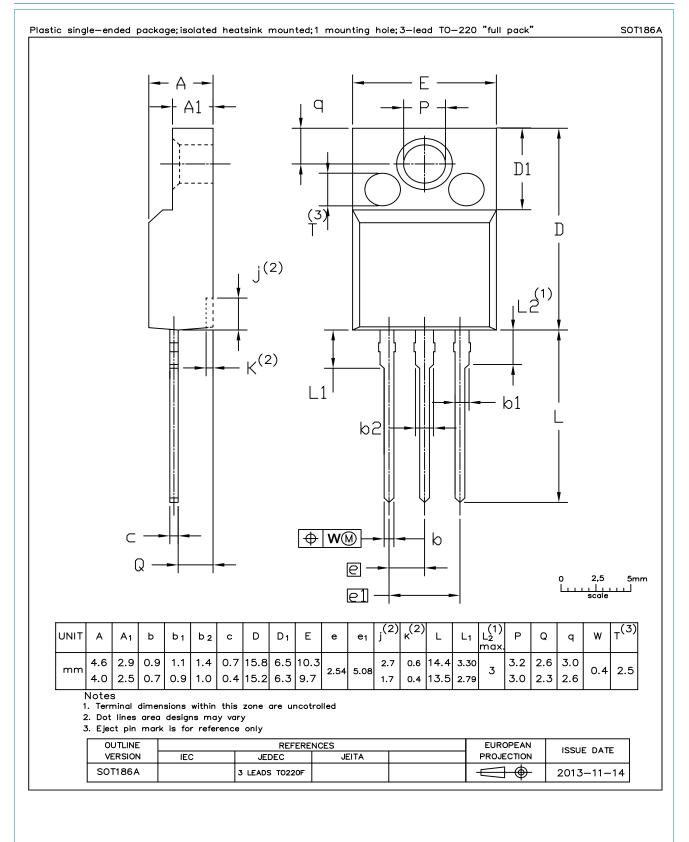
| Parameter | Conditions | Min | Тур | Max | Unit |
|-----------------------------------|--|---|---|---|------|
| aracteristics | | I | | | _ |
| gate trigger current | V_{D} = 12 V; I _T = 0.1 A; T2+ G+; T _j = 25 °C; <u>Fig. 7</u> | - | 2.5 | 10 | mA |
| | V_{D} = 12 V; I _T = 0.1 A; T2+ G-; T _j = 25 °C; <u>Fig. 7</u> | - | 4 | 10 | mA |
| | V _D = 12 V; I _T = 0.1 A; T2- G-; T _j = 25 °C; <u>Fig. 7</u> | - | 5 | 10 | mA |
| | V_{D} = 12 V; I _T = 0.1 A; T2- G+; T _j = 25 °C; <u>Fig. 7</u> | - | 11 | 25 | mA |
| latching current | V_{D} = 12 V; I _G = 0.1 A; T2+ G+; T _j = 25 °C; Fig. 8 | - | 3 | 15 | mA |
| | V_{D} = 12 V; I _G = 0.1 A; T2+ G-; T _j = 25 °C; Fig. 8 | - | 10 | 20 | mA |
| | $V_D = 12 \text{ V}; \text{ I}_G = 0.1 \text{ A}; \text{ T2- G-};$ T _j = 25 °C; <u>Fig. 8</u> | - | 2.5 | 15 | mA |
| | $V_D = 12 \text{ V}; \text{ I}_G = 0.1 \text{ A}; \text{ T2- G+};$ T _j = 25 °C; <u>Fig. 8</u> | - | 4 | 20 | mA |
| holding current | V _D = 12 V; T _j = 25 °C; <u>Fig. 9</u> | - | 2.2 | 15 | mA |
| on-state voltage | I _T = 5 A; T _j = 25 °C; <u>Fig. 10</u> | - | 1.4 | 1.7 | V |
| gate trigger voltage | V _D = 12 V; I _T = 0.1 A; T _j = 25 °C; Fig. 11 | - | 0.7 | 1 | V |
| | V _D = 400 V; I _T = 0.1 A; T _j = 125 °C; <u>Fig. 11</u> | 0.25 | 0.4 | - | V |
| off-state current | V _D = 600 V; T _j = 125 °C | - | 0.1 | 0.5 | mA |
| characteristics | · · · · · · | I | | | |
| rate of rise of off-state voltage | V_{DM} = 402 V; T _j = 125 °C; (V _{DM} = 67% of V _{DRM}); exponential waveform; gate open circuit | - | 50 | - | V/µs |
| gate-controlled turn-on time | $V_{\rm D}$ = 600 V; I _{TM} = 6 A; I _G = 0.1 A; dI _G /dt = 5 A/µs | - | 2 | - | μs |
| | aracteristics gate trigger current gate trigger current latching current holding current on-state voltage gate trigger voltage off-state current characteristics rate of rise of off-state voltage gate-controlled turn-on | aracteristics gate trigger current $V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; \text{ T2+ G+}; \\ T_J = 25 ^{\circ}\text{C}; Fig. 7 \\ V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; \text{T2+ G-}; \\ T_J = 25 ^{\circ}\text{C}; Fig. 7 \\ V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; \text{T2- G-}; \\ T_J = 25 ^{\circ}\text{C}; Fig. 7 \\ V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; \text{T2- G+}; \\ T_J = 25 ^{\circ}\text{C}; Fig. 7 \\ V_D = 12 \text{ V}; I_G = 0.1 \text{ A}; \text{T2+ G+}; \\ T_J = 25 ^{\circ}\text{C}; Fig. 8 \\ V_D = 12 \text{ V}; I_G = 0.1 \text{ A}; \text{T2+ G+}; \\ T_J = 25 ^{\circ}\text{C}; Fig. 8 \\ V_D = 12 \text{ V}; I_G = 0.1 \text{ A}; \text{T2+ G-}; \\ T_J = 25 ^{\circ}\text{C}; Fig. 8 \\ V_D = 12 \text{ V}; I_G = 0.1 \text{ A}; \text{T2- G-}; \\ T_J = 25 ^{\circ}\text{C}; Fig. 8 \\ V_D = 12 \text{ V}; I_G = 0.1 \text{ A}; \text{T2- G+}; \\ T_J = 25 ^{\circ}\text{C}; Fig. 8 \\ \hline V_D = 12 \text{ V}; I_G = 0.1 \text{ A}; \text{T2- G+}; \\ T_J = 25 ^{\circ}\text{C}; Fig. 8 \\ \hline V_D = 12 \text{ V}; I_G = 0.1 \text{ A}; \text{T2- G+}; \\ T_J = 25 ^{\circ}\text{C}; Fig. 8 \\ \hline V_D = 12 \text{ V}; I_G = 0.1 \text{ A}; \text{T2- G+}; \\ T_J = 25 ^{\circ}\text{C}; Fig. 10 \\ \hline \text{on-state voltage} \qquad I_T = 5 \text{ A}; T_J = 25 ^{\circ}\text{C}; Fig. 9 \\ \hline \text{on-state voltage} \qquad I_T = 5 \text{ A}; T_J = 25 ^{\circ}\text{C}; Fig. 10 \\ \hline V_D = 400 \text{ V}; I_T = 0.1 \text{ A}; T_J = 125 ^{\circ}\text{C}; \\ Fig. 11 \\ \hline V_D = 400 \text{ V}; I_T = 0.1 \text{ A}; T_J = 125 ^{\circ}\text{C}; \\ Fig. 11 \\ \hline V_D = 400 \text{ V}; I_T = 125 ^{\circ}\text{C}; \\ Fig. 11 \\ \hline \text{off-state current} \qquad V_D = 600 \text{ V}; T_J = 125 ^{\circ}\text{C}; (V_{DM} = 67\% \text{ of } V_{DRM}); \text{ exponential waveform}; \text{ gate open circuit} \\ \hline \text{gate-controlled turn-on} \qquad V_D = 600 \text{ V}; I_T = 6 \text{ A}; I_G = 0.1 \text{ A}; \\ \end{array} $ | $ \begin{array}{ c c c c c c c c c c c c c c c c c c c$ | $ \begin{array}{ c c c c c c c c c c c c c c c c c c c$ | |



BT136X-600E



12. Package outline



13. Legal information

Data sheet status

| Document status [1][2] | Product status [3] | Definition |
|--------------------------------------|-----------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
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BT136X-600E 4Q Triac

14. Contents

| 1. General description | 1 |
|-------------------------------|----|
| 2. Features and benefits | 1 |
| 3. Applications | 1 |
| 4. Quick reference data | 1 |
| 5. Pinning information | 2 |
| 6. Ordering information | 2 |
| 7. Marking | 2 |
| 8. Limiting values | 3 |
| 9. Thermal characteristics | 6 |
| 10. Isolation Characteristics | 6 |
| 11. Characteristics | 7 |
| 12. Package outline | 10 |
| 13. Legal information | 11 |
| 14. Contents | 13 |

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